

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application.

1-36. (Canceled)

37. (New) A patterning method, comprising:

depositing a first liquid material to a first part between a first indent of a plurality of indents formed in a surface of a substrate and a second indent of the plurality of indents;

depositing a second liquid material to a second part between the first indent and a third indent of the plurality of indents; and

no material being deposited to a third part between the second indent and a fourth indent of the plurality of indents.

38. (New) The patterning method according to claim 37, the first liquid material being the same as the second liquid material.

39. (New) The patterning method according to claim 37, the first liquid material being different from the second liquid material.

40. (New) The patterning method according to claim 37, wherein a group of indents included in the first indent being formed between the first part and the second part.

41. (New) The patterning method according to claim 37, wherein the first indent has a width tapering towards the bottom.

42. (New) The patterning method according to claim 37, wherein the first indent has a width widening towards the bottom.

43. (New) A patterning method comprising:

 depositing a liquid material onto an indent region having wall portions which have slopes relative to a surface of a substrate; and

the slopes being arranged such that the indent region having widths widening towards a bottom of the indent region.

44. (New) The patterning method according to claim 43 wherein the indent region is formed with a cross-sectional profile to provide a secondary barrier to further control the spread of the material over the surface.

45. (New) The patterning method according to claim 44 wherein the indent region is provided with a castellated cross-sectional profile.

46. (New) The patterning method according to claim 44 wherein the indent region is provided with a saw-tooth cross-sectional profile.

47. (New) The patterning method according to claim 44 comprising providing first and second indent regions of elongate shape and impressing a further elongate indent region arranged between but spaced from the first and second indent regions, the further indent region having a substantially planar bottom surface.

48. (New) A method of manufacturing an electronic device, the method comprising: making a pattern by the patterning method according to claim 37.

49. (New) The method according to claim 48,  
the first liquid material including a semiconductor material, and the second liquid material including a semiconductor material.

50. (New) The method according to claim 49,  
a source of a transistor and a drain of the transistor being formed in the first part and the second part, respectively; and  
a channel of the transistor being formed between the first part and the second part.

51. (New) A patterning method comprising:  
forming an indent region in the surface of a substrate;

depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region; wherein the indent region is formed with a cross-sectional profile to provide a secondary barrier to further control the spread of the material over the surface; and wherein the material is selected to comprise a semiconductor material and the selected locations comprise the surface between the elongate indent regions so as to provide source and drain regions for a thin film transistor having a channel length determined by the width of the further elongate indent regions and a channel width determined by the length of the further elongate indent region.

52. (New) A patterning method comprising:  
forming an indent region in the surface of a substrate;  
depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region; and  
adjusting the wetting characteristic of the surface of the substrate relative to the material to be deposited.

53. (New) A patterning method comprising:  
forming an indent region in the surface of a substrate;  
depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region;  
wherein the indent region is formed with a cross-sectional profile to provide a secondary barrier to further control the spread of the material over the surface; the method further comprising:  
providing first and second indent regions of elongate shape;

impressing a further elongate indent region arranged between but spaced from the first and second indent regions, the further indent region having a substantially planar bottom surface; and

wherein the first and second indent regions are selected to comprise the cross-sectional profile providing the secondary barrier.

54. (New) A patterning method comprising:

forming an indent region in the surface of a substrate;

depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region; and

wherein the indent region or regions is/are provided using an impression technique and the surface is impressed using a stamping die.

55. (New) A patterning method comprising:

forming an indent region in the surface of a substrate;

depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region; and

wherein the indent region or regions is/are provided using an impression technique and the surface is impressed using a moulding technique.

56. (New) A patterning method comprising:

forming an indent region in the surface of a substrate;

depositing a liquid material onto the surface at selected locations such that spread of the material over the surface is controlled by the indent region; and

providing two juxtaposed elongate indent regions and wherein the material is selected to comprise a conductive material and the selected locations comprise the surface between the elongate indent regions, thereby to provide an electrically conductive electrode.

57. (New) A patterning method comprising:

forming an indent region in the surface of a substrate;  
depositing a liquid material onto the surface at selected locations such that  
spread of the material over the surface is controlled by the indent region; and  
wherein the indent region or regions is/are provided using an impression  
technique.

58. (New) A patterning method for depositing a liquid onto a surface of a  
substrate; said method comprising:

forming a first and second indent in the surface, each indent having falling  
edges co-incident with the surface and spaced a distance apart;  
depositing said liquid between said indents; and  
selecting the distance such that a greater volume of liquid is deposited and  
retained than in the absence of at least one of the indents.

59. (New) A patterning method according to claim 58, in which said forming said  
first and second indents includes forming wall portions sloping relative to the surface.

60. (New) A method of manufacturing an electronic device, the method  
comprising: making a pattern by the patterning method according to claim 58.

61. (New) A patterning method for depositing a liquid onto a surface of a  
substrate, said method comprising:

forming a first and second indent in the surface, each indent having falling  
edges co-incident with the surface and spaced a distance apart;  
depositing said liquid between said indents; and  
selecting the distance such that a greater contact angle between the liquid and  
the surface is provided than in the absence of at least one of the indents.

62. (New) A patterning method according to claim 61, in which said forming said  
first and second indents includes forming wall portions sloping relative to the surface.

63. (New) A method of manufacturing an electronic device, the method comprising: making a pattern by the patterning method according to claim 61.

64. (New) A patterning method for depositing a liquid onto a surface of a substrate, said method comprising:

forming a first and second indent in the surface, each indent having falling edges co-incident with the surface and spaced a distance apart;

depositing said liquid between said indents; and

selecting the distance such that the diameter of the deposited liquid is greater than the distance.

65. (New) A patterning method according to claim 64, in which said forming said first and second indents includes forming wall portions sloping relative to the surface.

66. (New) A method of manufacturing an electronic device, the method comprising: making a pattern by the patterning method according to claim 64.

67. (New) A patterning method for depositing a liquid onto a surface of a substrate, said method comprising:

forming a first and second indent in the surface, each indent having falling edges co-incident with the surface and spaced a distance apart;

depositing said liquid between said indents; and

selecting the distance such that the thickness of the liquid deposited and retained is greater than in the absence of at least one of the indents.

68. (New) A patterning method according to claim 67, in which said forming said first and second indents includes forming wall portions sloping relative to the surface.

69. (New) A method of manufacturing an electronic device, the method comprising: making a pattern by the patterning method according to claim 67.